REMARKS/ARGUMENT

While it is believed that the Amendment filed on April 18, 2003 was fully responsive to the Office Action, it is being resubmitted with claims 6-11 being indicated as "withdrawn".

Reconsideration of the restriction requirement is once again respectfully requested. It is respectfully pointed out that the restriction requirement was predicated on there being a cured matrix resin, but the claims in this application never required a cured resin. Since the restriction requirement was predicated on an incorrect assumption and the classification of the two groups is identical, it is respectfully submitted that the restriction requirement should be withdrawn.

In the event that the Examiner does not withdraw the restriction requirement, it is respectfully requested that this response be treated as a petition and forwarded for decision thereon.

A series of additional dependent claims based on the third paragraph of page 6 of the application has been presented for consideration by the Examiner.

To expedite allowance of this application, the claims have been directed an adhesive composition which is the combination of a liquid polyamic acid which becomes a polyimide resin after curing and a ferrite powder. The polyamic resin before curing can easily be dissolved in an organic solid and a sufficient amount of ferrite powder can be added. In addition, it allows a thermally stable adhesive to be achieved. None of the references applied in the Office Action teach or suggest such a composition. It is therefore

unnecessary to specifically recite and traverse each individual rejection. None are valid for this reason.

The Ishino, JP '304 and Suzuki '557 and '412 references all teach a polyimide resin. None teach or suggest the use of a polyamic acid resin which is a material that becomes a polyimide resin having imide bonding after curing.

JP '363 and Tanino (U.S. '329 or EP '392) disclose a prepolymer obtained by the reaction of an unsaturated dicarboxylic bisimide with a polyamine having two amino groups. There is no teaching or suggestion of a liquid polyamic acid which becomes a polyimide resin after curing.

Acknowledgement of the art submitted in June 2001 is respectfully requested.

In view of the insufficiencies of the prior art, it is respectfully submitted that all of the rejections in this application should be withdrawn and the application is in condition to be allowed. Accordingly, the early issuance of a Notice of Allowance is respectfully solicited.

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Respectfully submitted,

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